



EXTERNAL INPUT/OUTPUT (I/O) & CABLE SOLUTIONS



FOR OPEN COMPUTE PROJECT (OCP) APPLICATIONS

TE Connectivity (TE) continues to be a leader in the industry with I/O solutions for 56G- and 112G-based interconnect solutions supporting 50G, 100G, 200G and 400G links from the data center server, through fabric and spine network layers and equipment for wide-area-network, data center-to-data center connections. Our solutions not only address the needs for high data rates but can also provide high density, high reliability, compatible solutions for robust interoperability. Our high performance cable assemblies can be tailored to support the mechanical and electrical requirements for our customers' applications.

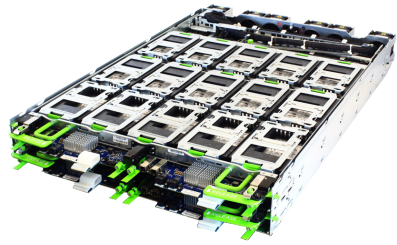
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EXTERNAL I/O & CABLE SOLUTIONS

STORAGE/ACCELERATOR



zQSFP+ Connectors & Cages

Platform: OCP NIC 3.0



Mini-SAS HD Connectors

Platforms: Lightning, Bryce Canyon



Mini-SAS HD Cable Assemblies

Platforms: Olympus



RACK



Cable Assemblies: Switch-to-Server, Direct Attach Copper

Platforms: Leopard, Yosemite, Wedge100, Tioga Pass



Cable Assemblies: Machine-to-Machine, Mini-SAS HD

Platforms: Lightning, Bryce Canyon, Big Basin



SWITCH



QSFP-DD Connectors & Cages

Platform: OCP NIC 3.0 (and future platforms)



OSFP Connectors & Cages

Platform: OCP NIC 3.0 (and future platforms)



zQSFP+ Connectors & Cages

Platforms: OCP NIC 3.0, Wedge100, Back Pack (and future platforms)



QSFP+ Connectors & Cages

Platforms: SixPack, Wedge



RJ45 Modular Jacks & Combo Jacks

Platforms: SixPack, OCP NIC 3.0



SERVER



zQSFP+ Connectors & Cages

Platform: Olympus

